

Appl. Ser. No. 10/737,240

Resubmission Amend A in Resp to O/A 5/26/05

**IN THE CLAIMS:**

Please cancel claims 1-20.

Please add claims 21-40.

A marked up version of the modified claims starts on page 04 in accordance with 37 § CFR 1.121 as follows: The changes in any amended claims are shown by strikethrough (for deleted matter) and underlining (for added matter). The status of each Claim is indicated adjacent the Claim Number.

Thereafter, starting on a separate page, (Page 08), is the Remarks portion in accordance with 37 CFR § 1.121.

Appl. Ser. No. 10/737,240

Resubmission Amend A in Resp to O/A 5/26/05

**Claims:**

1-20 (Cancelled)

21. (New) A method for cleaning at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies, the steps comprising:

applying a fluid to the at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies,

applying vibrational energy by at least one of mechanically coupling a vibrational energy source and the at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies and transferring the vibrational energy through the air directed towards the at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies to aid in drying the at least one of electronic assemblies and tooling related to manufacture of electronic assemblies by atomizing moisture droplets resident to the at least one of electronic assemblies and tooling related to manufacture of electronic assemblies.

22. (New) The method of claim 21, the method further comprising the step of:

applying vibrational energy to aid in cleaning drying of at least one of electronic assemblies and tooling related to manufacture of electronic assemblies.

23. (New) The method of claim 22, the method further comprising transferring the relational proximity of the vibrational energy source and the at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies to one another.

24. (New) The method of claim 21, the method further comprising transferring the relational proximity of the vibrational energy source and the at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies to one another.

Appl. Ser. No. 10/737,240

Resubmission Amend A in Resp to O/A 5/26/05

25. (New) The method of claim 21, the method further comprising:  
transferring vibrational energy through air to the at least one of electronic assembly, stencil, and tooling related to manufacture of electronic assemblies to aid in the drying process.
26. (New) A method for cleaning a solder stencil, the method comprising the steps:  
applying a fluid for cleaning the solder stencil, and  
applying vibrational energy by at least one of mechanically coupling a vibrational energy source and the solder stencil and transferring the vibrational energy through the air directed towards the solder stencil to aid in drying the solder stencil.
27. (New) The method of claim 26, the method further comprising the step:  
transferring the relational proximity of the vibrational energy source and the solder stencil to one another.
28. (New) The method of claim 27, the method further comprising the step:  
applying vibrational energy to the fluid to assist in a cleaning process.
29. (New) The method of claim 26, the method further comprising the step:  
applying vibrational energy to the fluid to assist in a cleaning process.
30. (New) The method of claim 29, the method further comprising the steps commonly associated with automated solder screen printing, the commonly associated steps of solder screen printing comprising aligning electronic pads of a printed circuit board and apertures of the solder stencil, passing solder paste across apertures of a stencil, and separating the printed circuit board and the solder stencil.
31. (New) The method of claim 26, the method further comprising the steps

Appl. Ser. No. 10/737,240

Resubmission Amend A in Resp to O/A 5/26/05

commonly associated with automated solder screen printing, the commonly associated steps of solder screen printing comprising aligning electronic pads of a printed circuit board and apertures of the solder stencil, passing solder paste across apertures of a stencil, and separating the printed circuit board and the solder stencil.

32. (New) The method of claim 26, the method further comprising the step:  
wiping the stencil with the wiping material.

33. (New) The method of claim 32, method further comprising the step:  
applying a vacuum force to aid in cleaning the stencil.

34. (New) The method of claim 26, the method further comprising the step:  
applying a vacuum force to aid in cleaning the stencil.

35. (New) A method for cleaning and drying a stencil, the method comprising the steps:  
aligning at least one of a printed circuit board to the stencil and an Integrated Circuit (IC) Wafer, the stencil comprising at least one aperture,  
positioning the printed circuit board proximate the stencil;  
passing a printable medium across the at least one aperture of the stencil to apply a pattern of printable medium onto the printed circuit board,  
applying a fluid based cleaning process to at least one of the stencil and a wiping material; and  
applying vibrational energy by at least one of through the air, via mechanical contact to the stencil, and to the wiping material, to aid in and drying the stencil.

36. (New) The method of claim 35, the method further comprising the step:

Appl. Ser. No. 10/737,240

Resubmission Amend A in Resp to O/A 5/26/05

applying the vibrational energy to aid in cleaning the stencil.

37. (New) The method of claim 35, the method further comprising the step:  
wiping the stencil with the wiping material.

38. (New) The method of claim 35, the method further comprising the step:  
applying a vacuum force to aid in cleaning the stencil.

39. (New) The method of claim 36, the method further comprising the step:  
solidifying said printable medium applied onto the IC wafer.

40. (New) The method of claim 36, the method further comprising the step:  
applying vibrational energy to assist in releasing the printable medium from said  
stencil.